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What is claimed is:

1. An electrostatic chuck comprising:
a circular ceramic plate having an electrostatic attractive
5 electrode;
a mounting surface for supporting a wafer formed on one of
the main surfaces of the circular ceramic plate;
an annular gas groove formed on the periphery of the mounting
surface in the form of concentric circles and a gas inlet which
10 communicates with the annular gas groove; and
a circular gas recess formed inside the circular ceramic
plate, and a gas inlet which communicates with the circular gas
recess,
wherein the annular gas groove and the circular gas recess
15 are independently separated from each other by a first annular
rib protrusion with a plurality of dotted protrusions being
disposed within both the annular gas groove and the circular
gas recess.
2. The electrostatic chuck according to claim 1, wherein
20 the circular gas recess has a diameter which is set to 70 to
95% of the outer diameter of the mounting surface.
3. The electrostatic chuck according to claim 1, wherein
the first annular rib protrusion surrounded by the outer
circumference of the circular gas recess and the inner
25 circumference of the annular gas groove has a width in a range

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of 0.5 to 5 mm, and an second annular rib protrusion surrounded by the outer circumference of the mounting surface and the outer circumference of the annular gas groove has a width in a range of 1 to 5 mm.

5 4. The electrostatic chuck according to claim 1, wherein:

the ratio S1/S2 of the area S1 of the circular gas recess to a total area S2 of the upper surfaces of the dotted protrusions disposed inside the circular gas recess is set in a range of 1 to 5; and

10 the ratio S3/S4 of an area S3 of the annular gas groove to a total area S4 of the upper surfaces of the dotted protrusions formed inside the annular gas groove is set in a range of 1 to 5.

15 5. The electrostatic chuck according to claim 1 wherein the circular ceramic plate has a heating element for heating the wafer buried in the ceramic plate or attached to the other main surface of the ceramic plate.